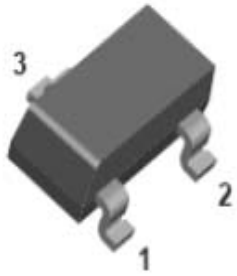
Digital Transistors (Built-in Resistors)



1. IN
2. GND
3. OUT

SOT−323

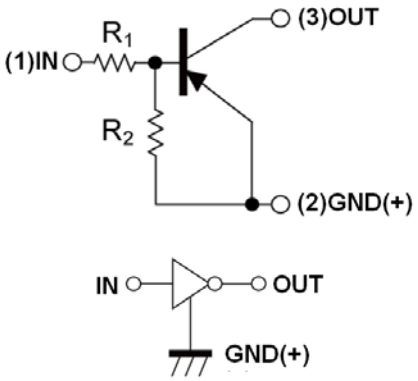
Features

●Epoxy meets UL-94 V-0 flammability rating
●Moisture Sensitivity Level 1
●Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors
●Surface mount package ideally Suited for Automatic Insertion
●PNP

Mechanical Data

- **Package**: SOT-323
- **Terminals**: Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Marking:** 94

■Equivalent circuit



■Maximum Ratings (Ta=25℃ Unless otherwise specified)

Item	Symbol	Unit	Conditions	Value
Supply Voltage	V_{CC}	V		-50
Input Voltage	V_{IN}	V		-40 to +6
Output Current	I_O	mA		-100
Power Dissipation	P_D	mW		200
Junction Temperature	T_J	℃		150
Storage Temperature	T_{STG}	℃		-55 to +150

■Electrical Characteristics (Ta=25℃ unless otherwise specified)

Item	Symbol	Unit	Conditions	Min	Typ	Max
Input voltage	$VI_{(off)}$	V	Vcc=-5V,Ic=-100uA	-0.3		
	$VI_{(on)}$	V	Vo=-0.3V,Ic=-1mA			-1.4
Output voltage	$Vo_{(on)}$	V	Io /Ii =-5mA/-0.25 mA			-0.3
Input Current	I_I	mA	Vi=5V			-0.88
Output current	$I_{O(off)}$	uA	Vcc=-50V, Vi=0			-0.5
DC current gain	GI		Vo=-5V, Io =-5mA	68		
Input resistance	R_1	kΩ		7	10	13
Resistance ratio	R_2/R_1			3.7	4.7	5.7
Transition frequency	fT	MHz	Vo=-10V,Io=-5mA,f=100MHz		250	

■ Ordering Information (Example)

PREFERED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
DTA114YUA	F2	Approximate 0.005	3000	30000	120000	7” reel

■ **Characteristics** (Typical)

Fig. 1 - DC Current Gain Characteristics

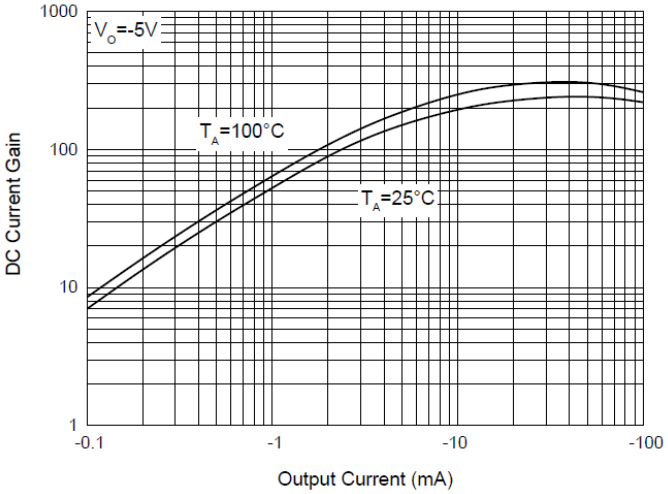


Fig. 2 - Input Voltage (on) Characteristics

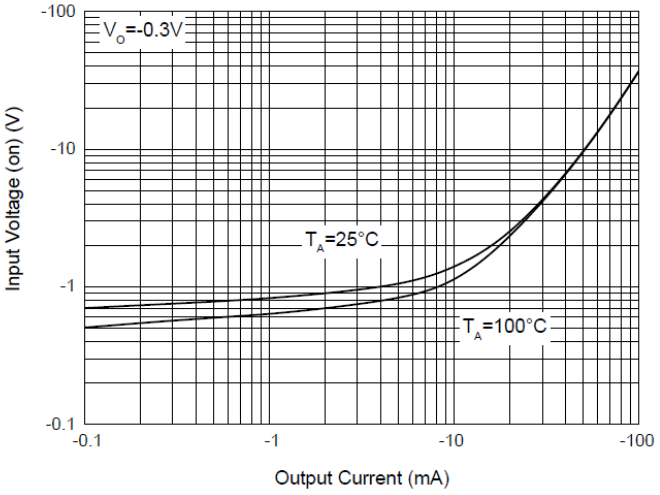


Fig. 3 - Input Voltage (off) Characteristics

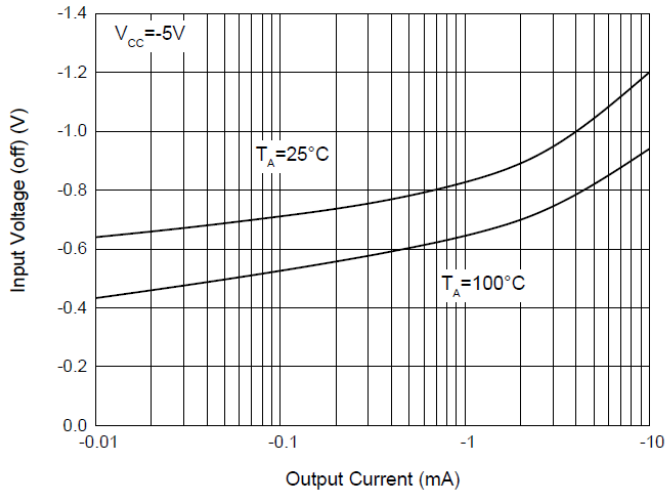


Fig. 4 - Output Voltage Characteristics

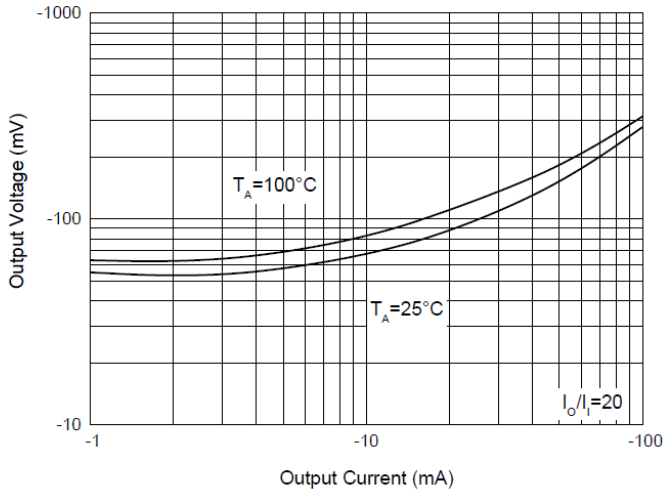
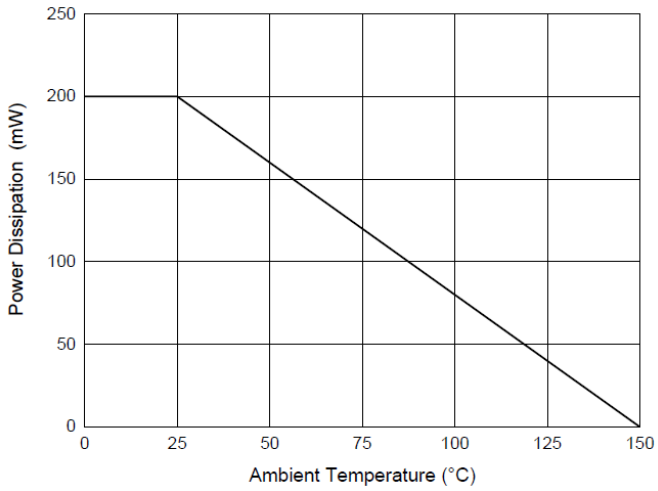
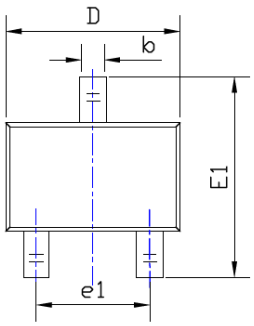


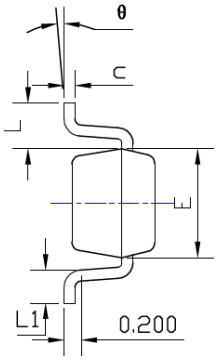
Fig. 5 - Power Derating Curve



■ SOT-323 Package Outline Dimensions

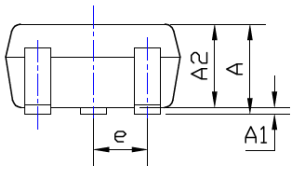


TOP VIEW

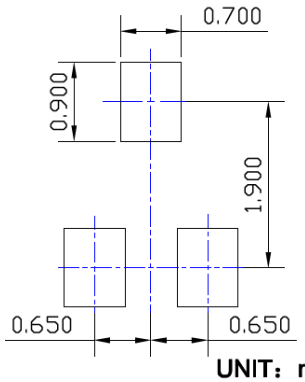


SIDE VIEW

DIMENSIONS				
SYMBOL	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	0.035	0.043	0.900	1.100
A1	0.000	0.004	0.000	0.100
A2	0.035	0.039	0.900	1.000
b	0.006	0.016	0.150	0.400
c	0.004	0.010	0.100	0.250
D	0.071	0.087	1.800	2.200
E	0.045	0.053	1.150	1.350
E1	0.085	0.096	2.150	2.450
e	0.026TYP		0.650TYP	
e1	0.047	0.055	1.200	1.400
L	0.021REF		0.525REF	
L1	0.010	0.018	0.260	0.460
θ	0°	8°	0°	8°



SIDE VIEW



UNIT：mm

SUGGESTED SOLDER PAD LAYOUT

NOTE:
1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.

Note:
1. All dimensions are in millimeters (mm) unless otherwise specified.
[所有尺寸均以毫米为单位，除非另有说明]
2. General tolerances: ±0.10mm unless otherwise specified.
[通用公差为±0.10mm，除非另有说明]
3. Dimensions and tolerances per ASME Y14.5M-2018.
[尺寸和公差遵循 ASME Y14.5M-2018 标准]
4.All dimensions shown are exclusive of burrs and gate residues.
Burrs and gate vestiges shall not exceed 0.15 mm in maximum.
[所有尺寸均不包括毛刺和浇口残留。毛刺与浇口残留的尺寸最大不得超过 0.15mm]
5.Dimension b does not include dambar protrusion of max 0.100 mm per side.
[尺寸b不包括单边最大0.100 MM的中筋凸出部分]
6.Dimensions D and E are the overall extreme outer dimensions of the mold compound. These dimensions exclude mold flash, lead flash, protrusions and burrs but include the maximum allowable mold mismatch.
[D和E是塑封体的外部极限尺寸，不包括包封溢料、内引线溢料、凸出部分以及胶体毛刺，但是包含了包封错位的最大尺寸]
7.Formed leads shall be planar with respect to one another within a maximum of 0.076 mm relative to the seating plane.
[成型的管脚应为同一平面，共面性最大为0.1mm]
8. ★It is the key size.
[★ 标记为关键尺寸]

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